

OPTICAL SEMICONDUCTOR ELEMENT MOUNTING PACKAGE, AND OPTICAL
SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT

A highly reliable package for mounting an optical semiconductor element in which good adhesion is ensured between a resin molding and a lead electrode, and an optical semiconductor device employing it. The package for mounting an optical semiconductor element has a recess to be an optical semiconductor element mounting region and is characterized in that a resin molding composed of a thermosetting light reflecting resin composition forming at least the side face of the recess is integrated with at least a pair of positive and negative lead electrodes arranged oppositely to form a part of the bottom face of the recess and the bonding surface of the resin molding and the lead electrode has no gap. An optical semiconductor device employing it is also provided.

Fig. 1